

Abstract

E11-P17

The apparatus, in preparation of soft soldering semiconductor chips to a substrate (6), is for the shaping of spherically domed liquid portions of solder (8) into flat solder applications (8"), as evenly distributed as possible and correctly positioned on the substrate. On a shaft (10) which can be lifted and lowered, a punch (20) with a punch surface (22) is guided vertically, spring mounted and slewable all around the axis of motion (16) and also frictionally engaged. The punch (20) is provided with distance keeping means - e.g. in the form of a circumferential rim (24) - which extend beyond the punch surface (22) and are intended for touching down on the substrate (6). In each operation cycle the punch (20) is automatically aligned to the substrate (6). Since the punch (20) is self-adjusting with respect to the shaft (10), it is unnecessary to maintain an exactly defined height position above the substrate.

(Fig. 2)

This Sheet Has Been Replaced

